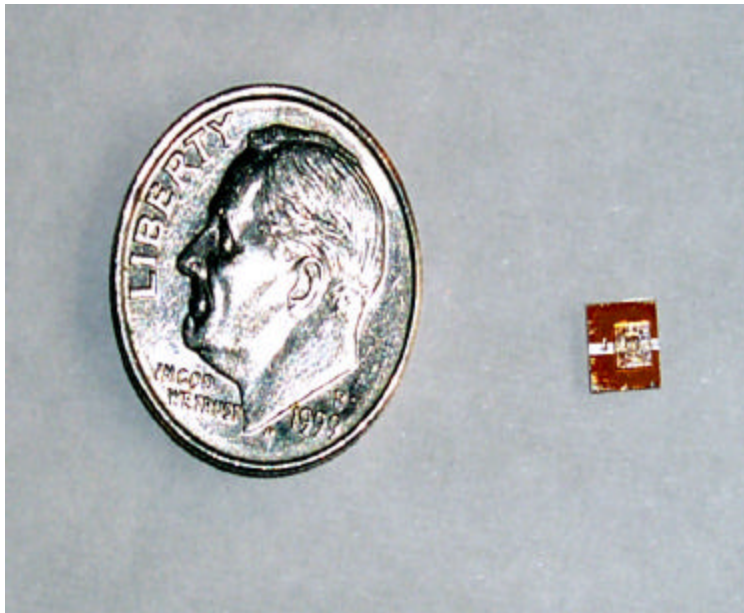




Design and Development of Micro Energetic Initiators (MEI) NDIA Fuze Conference 04/09/2003



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THE TEAM



E TACOM-ARDEC

- ◆ Brian Fuchs
- ◆ Gartung Cheng
- ◆ Neha Mehta
- ◆ Gerard Gillen
- ◆ Mark Mezger
- ◆ Mark Gelak
- ◆ Charles Robinson
- ◆ Mantech & JSSAP Funding

E Geo–Centers, Inc.

- ◆ Daniel Stec III

E Tanner Research Assoc.

- ◆ Amish Desai



INTRODUCTION

- A joint ARMY/Industry program to develop a process for manufacturing MEI for MEMS S&A devices
- Current issues with traditional S&A that can be resolved with MEMS S&As
 - **Cost**
 - Weight
 - Size



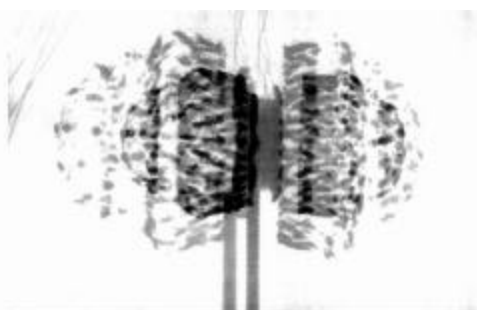
OBJECTIVE

- **Program Overall Objective:** Develop low cost Safe and Arm System for the XM-29 Integrated Airburst Weapon System
- **Our Objective:**
 - Develop low energy compact bridge design
 - Use bridge design in developing an MEI



Leadership
Teaming
Communication
Employee Support
Strategic Thinking
Organizational Climate

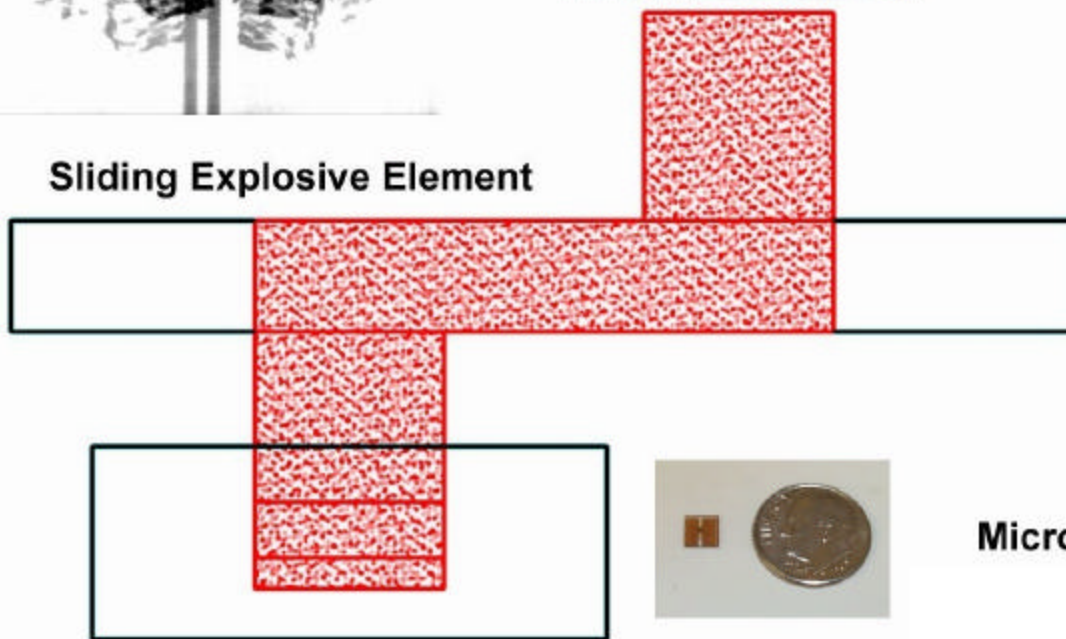
Schematic



Sliding Explosive Element



OICW Warhead



Micro Energetic Initiator

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MEI ISSUES

- Cost
 - Loadability
 - Producibility

➤ While maintaining Reliability

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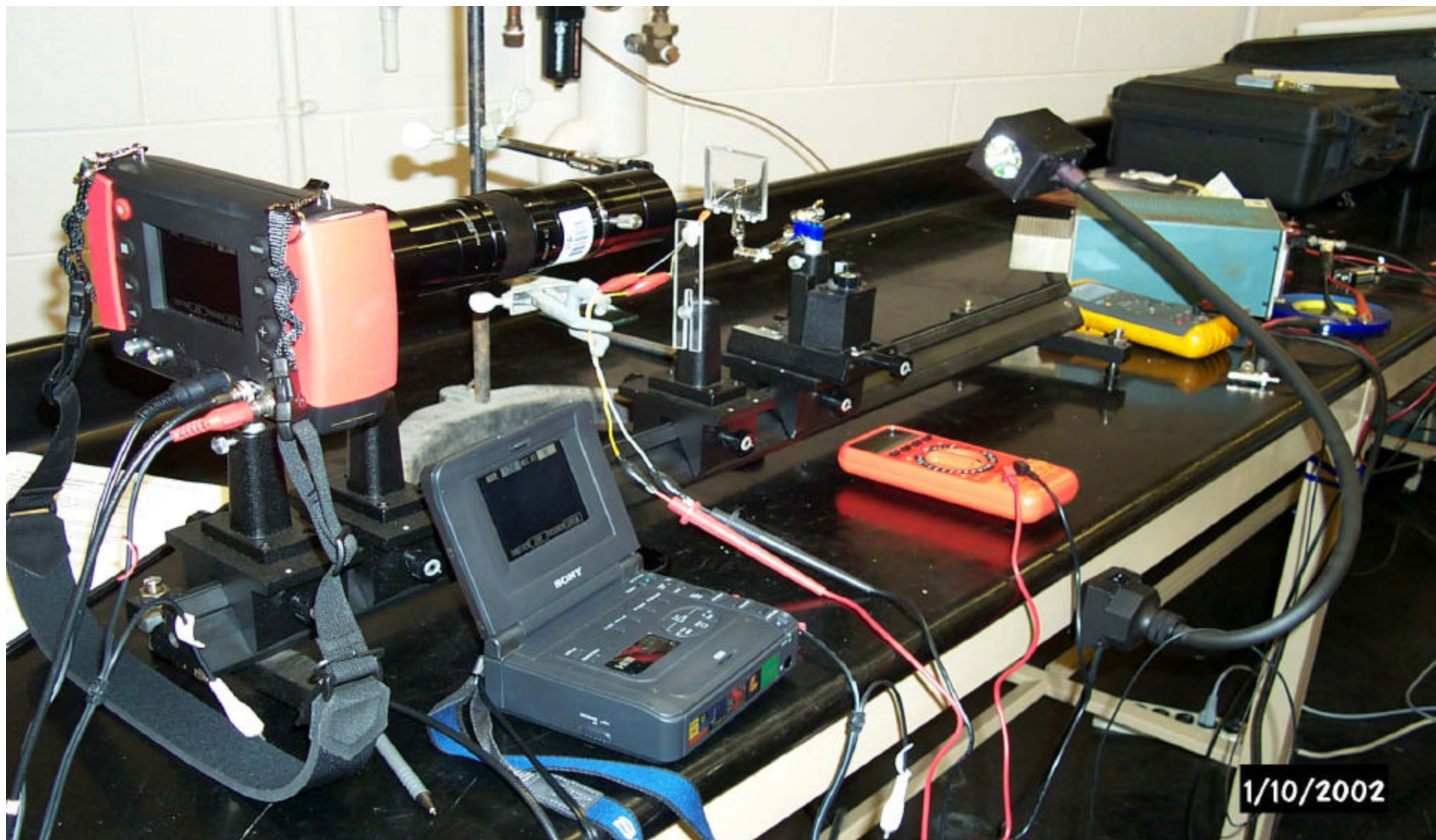


MEI Development

- 4 generations of ARDEC/Tanner Bridges
 - Flat geometry
 - Thin film heating element
 - Semiconductor Industry Procedures
- COTS Vishay Bridges
- Loaded with Lead Styphnate
- Obtained Firing voltage with XM29 firing circuit

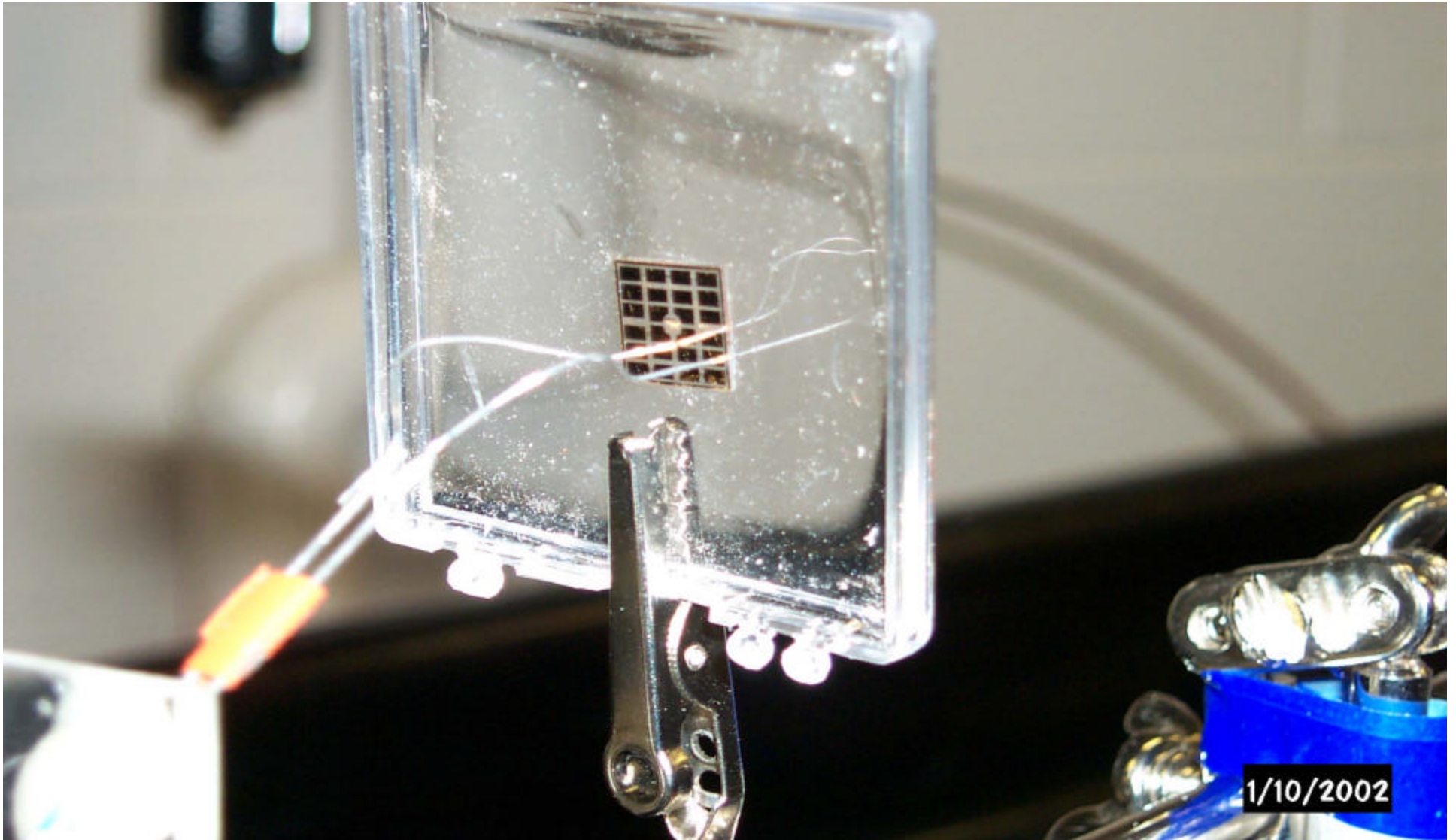


Videography Test Setup





Header with leads





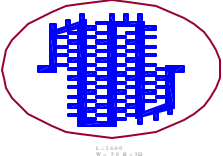
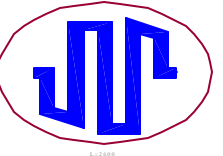
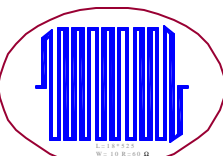
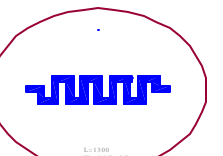
Functioning of 1st generation ARDEC/Tanner Fixture



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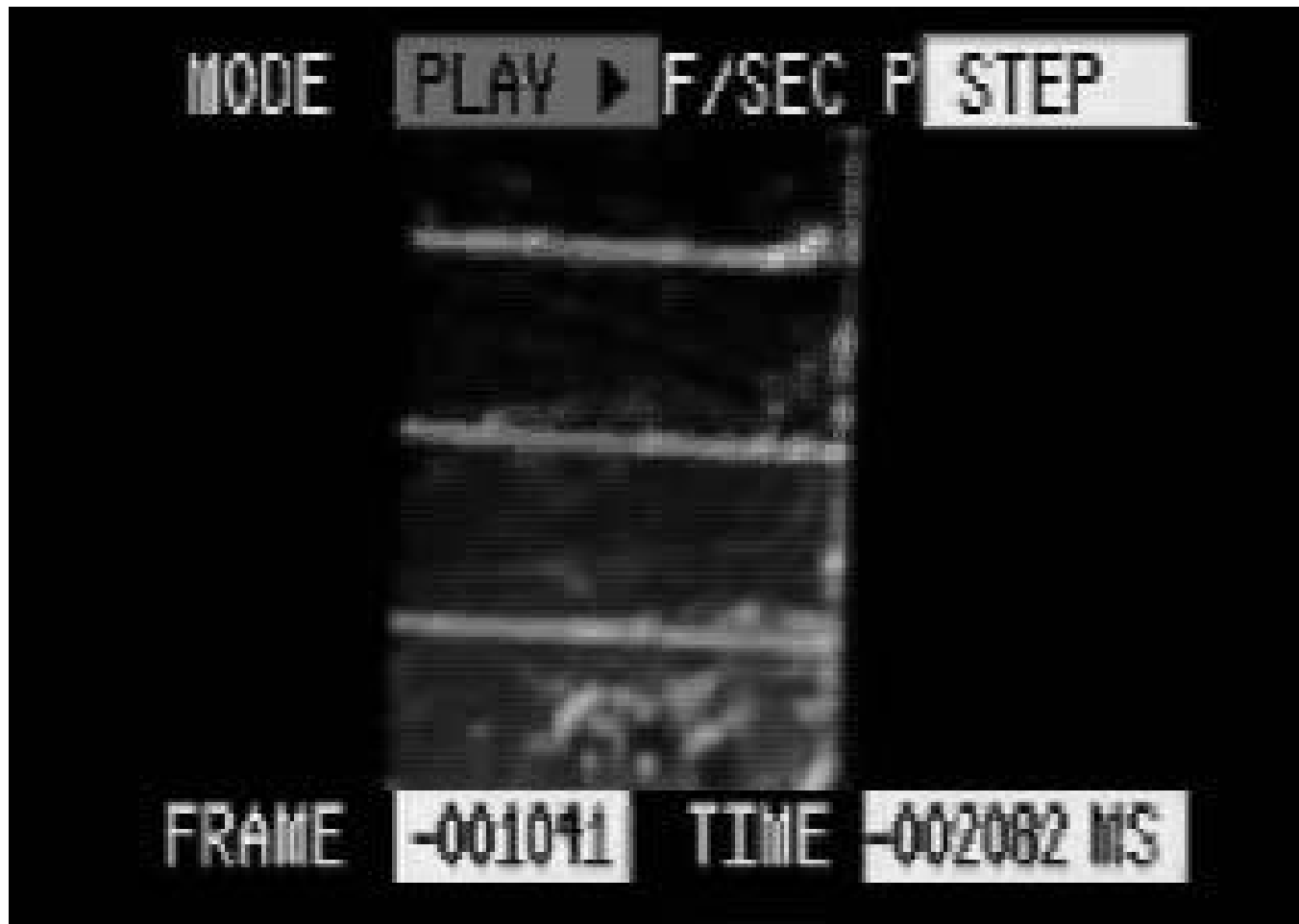
ARDEC/Tanner 1st generation Bridges

Unit	Measured Resistance (Ω)	Firing Voltage (V)
	4.7	10
	2.8	10
	54.6	9V Battery
	2.8	6

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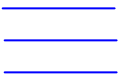

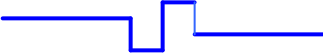
ARDEC/Tanner 2nd Generation



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2nd Generation Headers Fired with Lead Styphnate





Unit	Measured Resistance (Ω)	Firing Voltage (V)
	1.6	3
	3.6	4
	2.4	2.5
	3.6	4

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3rd generation of ARDEC/Tanner Bridges loaded with Lead Styphnate



Unit	Measured Resistance (Ω)	Voltage (V)
	1.3	3.0
	1.8	2.5
	1.5	2.75
	1.9	3.0

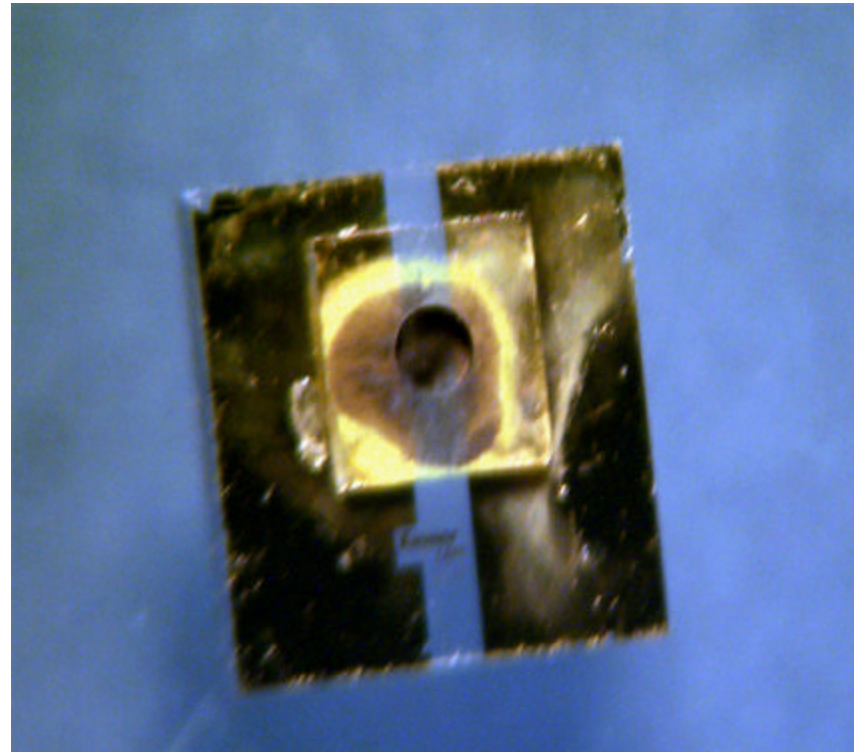
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4th generation of ARDEC/Tanner Bridges



- Photoresist Insulated Bridges







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4th Generation Headers with polyimide substrate

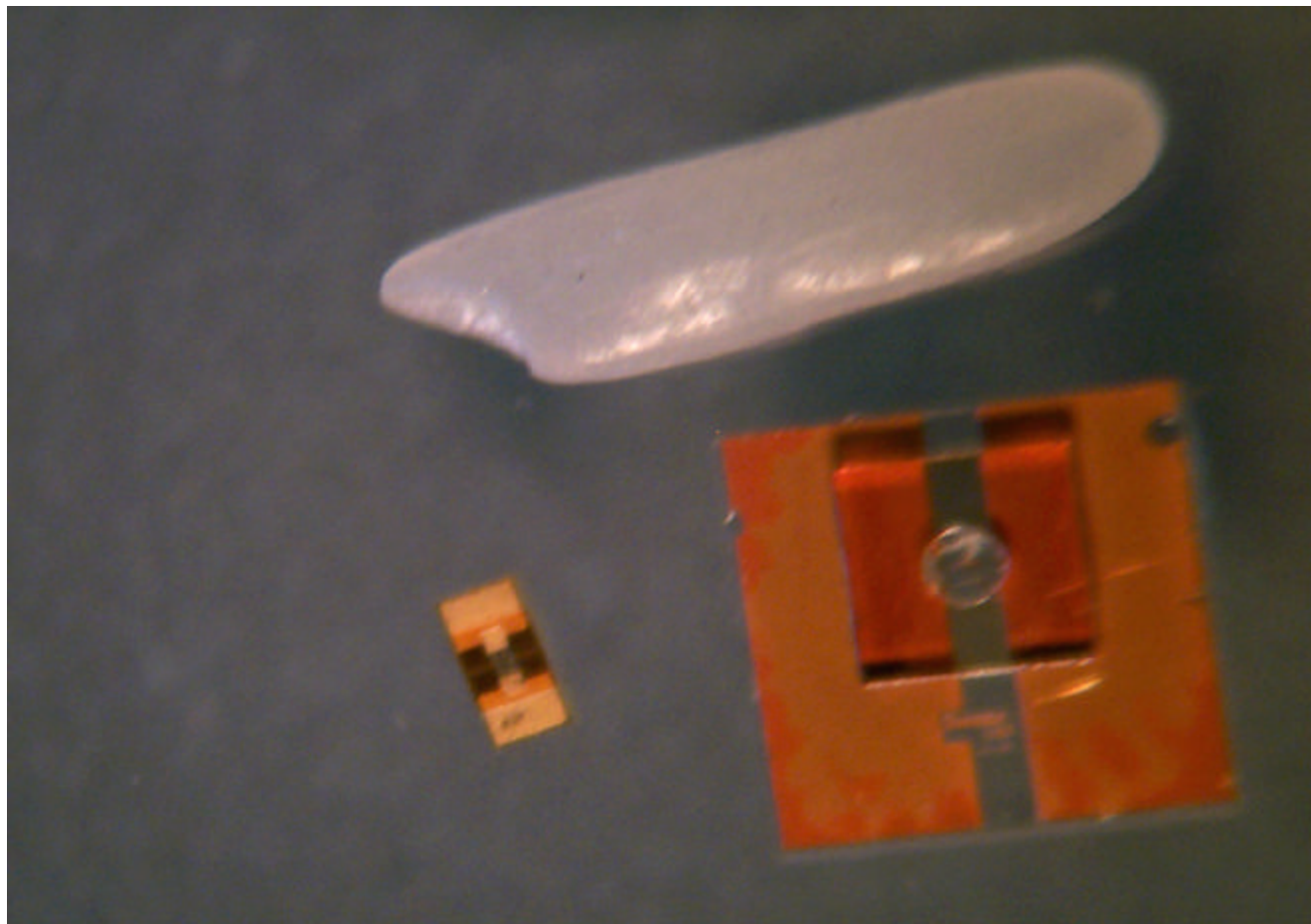


Unit	Measured Resistance (Ω)	Bruceton test Results
	1.1	$\hat{u} = 1.43$ $s = 0.068$
	2.3	$\hat{u} = 1.54$ $s = 0.056$
	1.8	$\hat{u} = 1.23$ $s = 0.051$
	1.5	$\hat{u} = 1.45$ $s = 0.213$

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Vishay & ARDEC/Tanner Headers



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Vishay Bridges

Unit	Measured Resistance (O)	Firing Voltage (V)	Bruceton test Result
1-H 2R	3.7	1.5	
1-H 5R	5.2	1.5	
2-L 2R	2.6	1.5	$\hat{u} = 1.407$ $s = 0.0831$
3-H 5R	5.7	3.0	
4-H 2R	2.5	2.5	
7-L 2R	2.5	4.0	



Conclusion

- Met voltage requirements with high reliability
- Developed MEI
- System has applicability to munitions system

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